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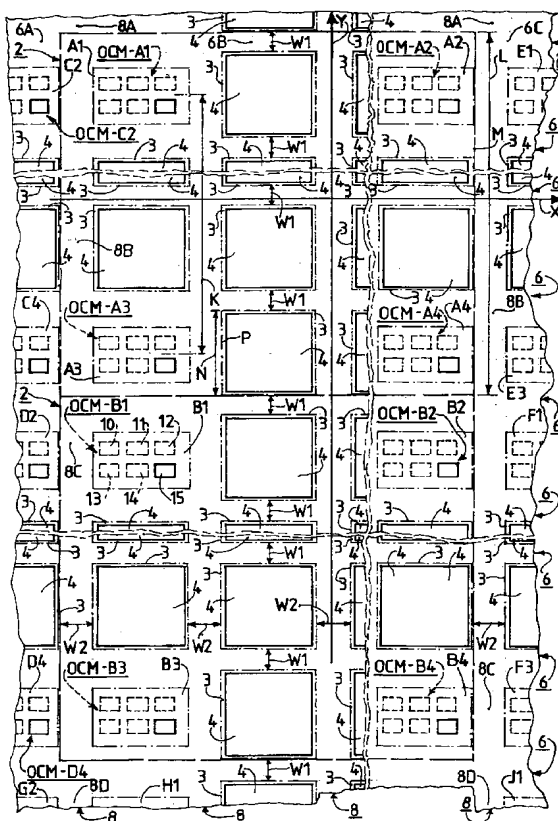
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[Continued on next page]

(54) Title: **WAFER WITH OPTICAL CONTROL MODULES IN EXPOSURE FIELDS**



(57) Abstract: In a wafer (1) with a number of exposure fields (2), each of which exposure fields (2) comprising a number of lattice fields (3) with an IC (4) located therein, two groups (5, 7) of dicing paths (6, 8) are provided and four control module fields (A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1) are assigned to each exposure field (2), each of which control module fields (A1, A2, A3, A4, B1, B2, B3, B4, C2, C4, D2, D4, E1, E3, F1, F3, G2, H1, J1) contains at least one optical control module (OCM-A1, OCM-A2, OCM-A3, OCM-A4, OCM-B1, OCM-B2, OCM-B3, OCM-B4, OCM-C2, OCM-D4) and lies within the exposure field (2) in question and is provided in place of at least one lattice field (3) and is arranged at a mutual minimum distance (K).